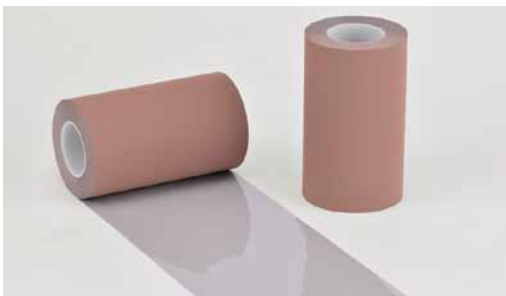


Conductive Bonding Film for FPC

Thermosetting type

CBF-300 / -W6



CBF-300/-W6 is a thermosetting conductive bonding film. When it is bonded on the stiffener, it can interconnect GND opening of FPC and a metallic stiffener at the same time the metallic stiffener can work as the shielding layer.

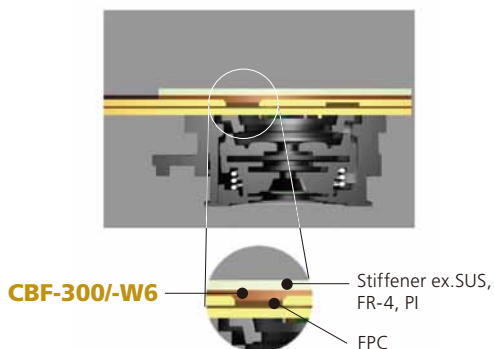
Features

- ▶ **Strengthening GND**
Interconnecting GND on FPC and metallic stiffener, CBF can strengthen GND interconnection.
- ▶ **High conductivity**
Stable-conductivity : Special metallic filler can keep stable conductivity.
- ▶ **Applicable to reflow-soldering**
Lead-free soldering is also applicable because of excellent heat - resistance thermosetting binder.
- ▶ **Outstanding adhesion**
To a wide range of materials : SUS, Copper, Gold, and various plastics : PI, FR-4, PET

Environmental regulation

Environmental regulation	CBF-300/-W6
Halogen free	Applicable
RoHS Directives	Applicable
Lead free reflow-soldering	Applicable

Application Example : Camera Module



Maintain a stable electrical interconnection between GND and SUS. Making Reinforcement plate a Hybrid one.

Cross Sectional Structure of CBF-300/-W6

